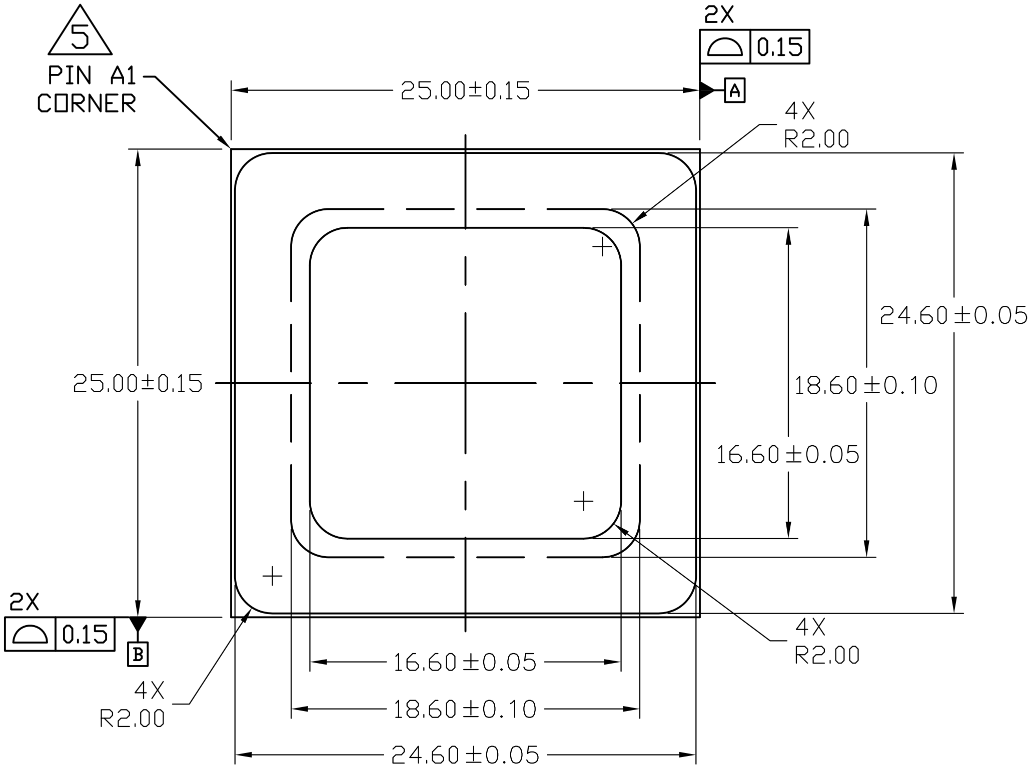
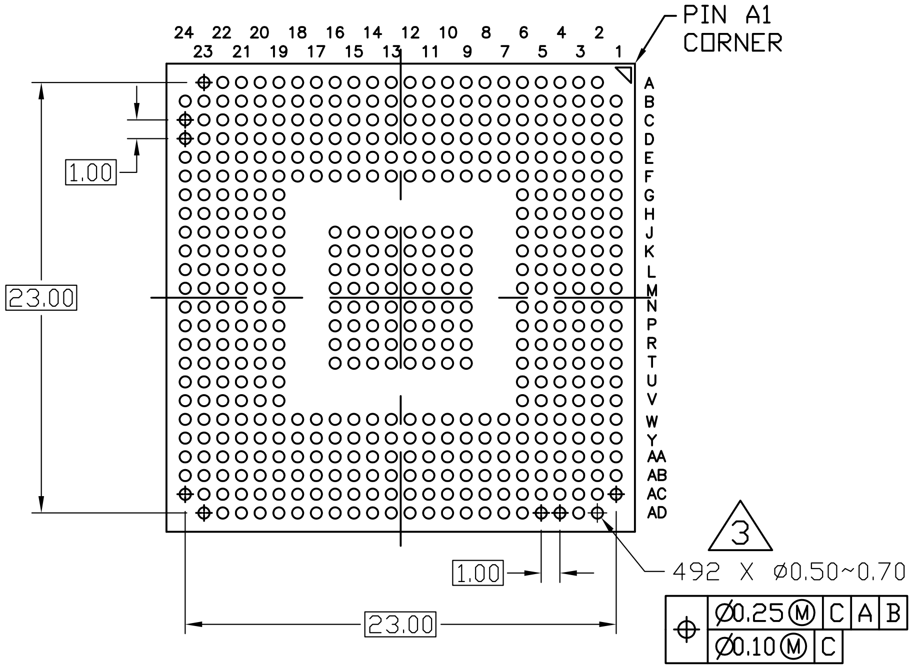
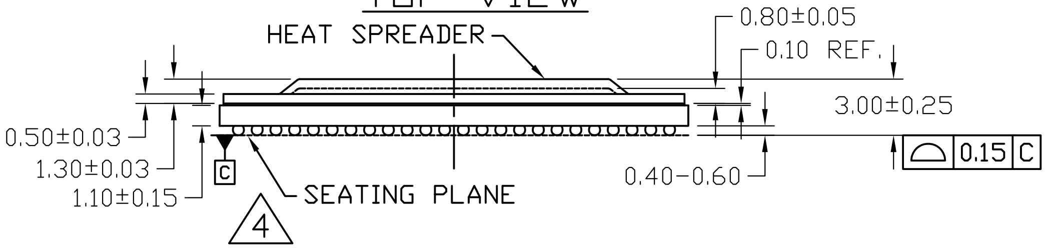


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM AND BALL DIA. IS 0.60MM.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.
6. MATERIAL MUST BE COMPLIANT WITH MAXIM SPECIFICATION 10-0131 FOR SUBSTANCE CONTENT, MUST BE Eu ROHS COMPLIANT WITHOUT EXEMPTION AND PB-FREE.
7. ALL DIMENSIONS APPLY TO LEADED (-), LEADFREE (+) AND ROHS EXEMPT (#) PKG. CODES.
8. PKG. CODES: X492FH-1, X492FH-2, X492HF+2.

-DRAWING NOT TO SCALE-

maxim integrated™

| | | | |
|---|---|---|---|
| TITLE:<br>PACKAGE OUTLINE, 492 BALLS HSBGAF, 25X25X3.00mm, 6 LAYERS, 1.00mm PITCH | | | |
| APPROVAL<br>EDEN CHEN<br>11/05/14 | DOCUMENT CONTROL NO.<br>21-0435 | REV.<br>E | 1/1 |